
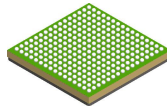


DATA BOOK PACKAGE OUTLINE

DRAFTER:	K. SINCERBOX	DATE:	10/25/2019			DIMENSIONS IN MILLIMETERS		
DESIGNER:		DATE:		 TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS		CODE IDENTITY NUMBER 01295		
CHECKER:	K. SINCERBOX	DATE:	05/26/2022					
ENGINEER:	S. O'CONNOR	DATE:	05/26/2022	ePOD, ALJ0256A / FCBGA, 256 BALL, 1 MM PITCH				
APPROVED:	D. CHIN & J. MARIANO	DATE:	05/26/2022					
RELEASED:	K. SINCERBOX	DATE:	05/26/2022					
TEMPLATE INFO:	EDGE# 4218519	DATE:	04/07/2016	SCALE NTS	SIZE A	4225401	REV B	PAGE 1 OF 5

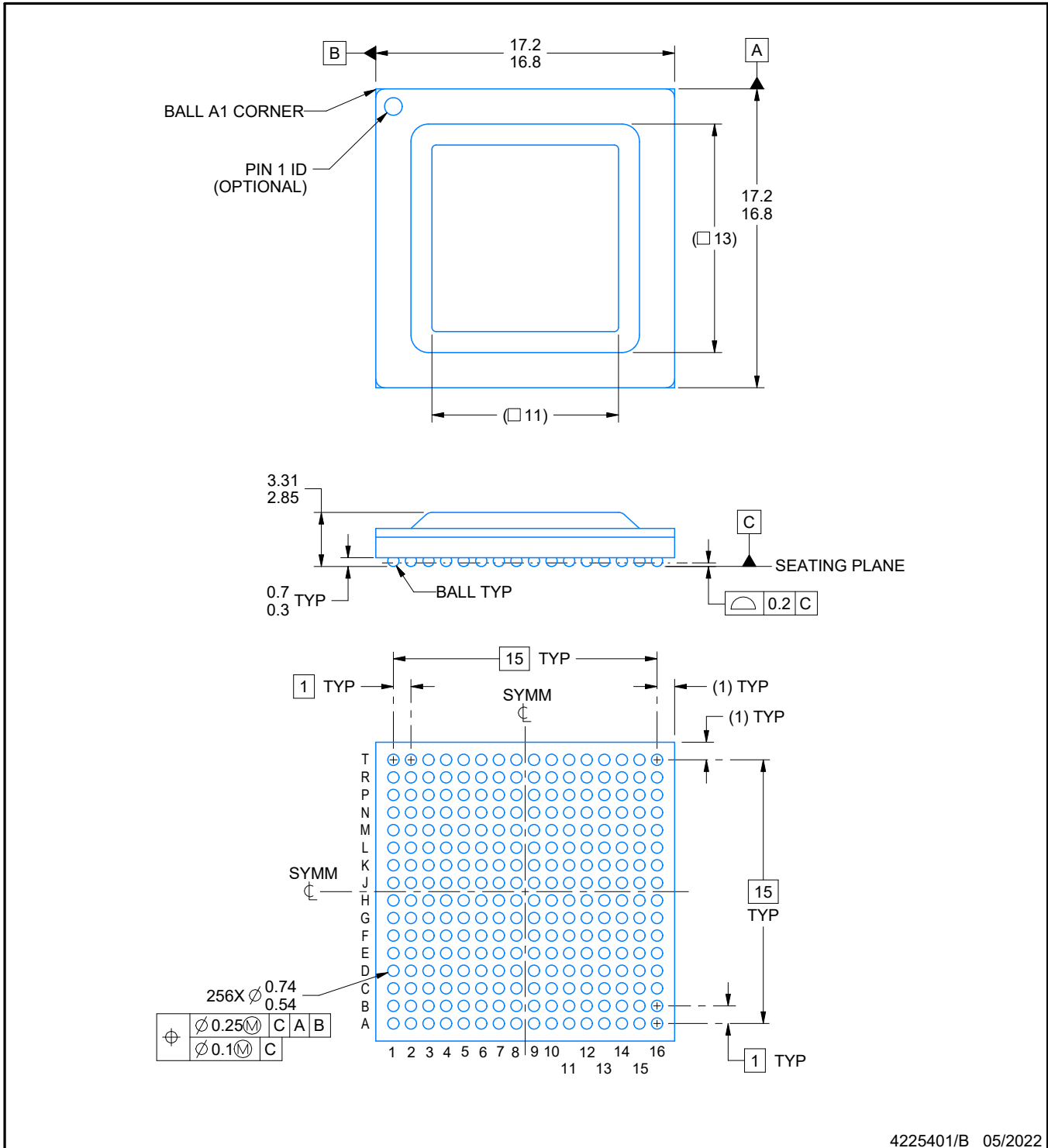
ALJ0256A



PACKAGE OUTLINE

FCBGA - 3.31 mm max height

BALL GRID ARRAY



4225401/B 05/2022

NOTES:

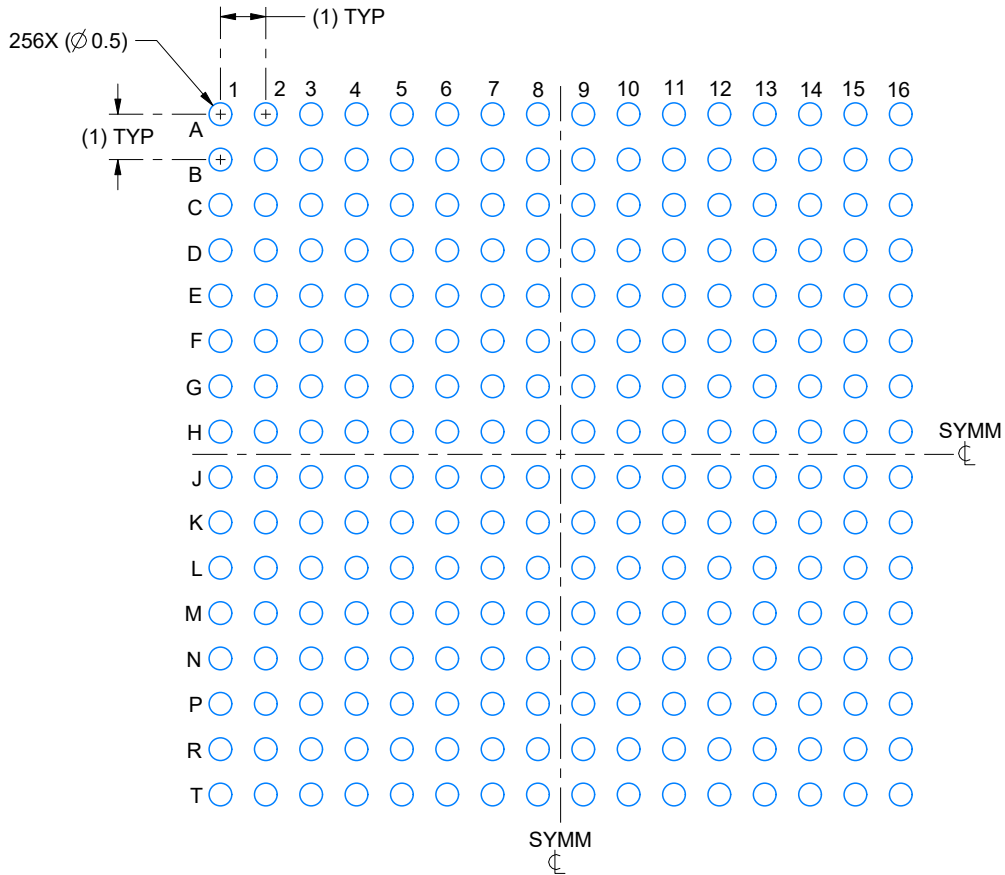
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

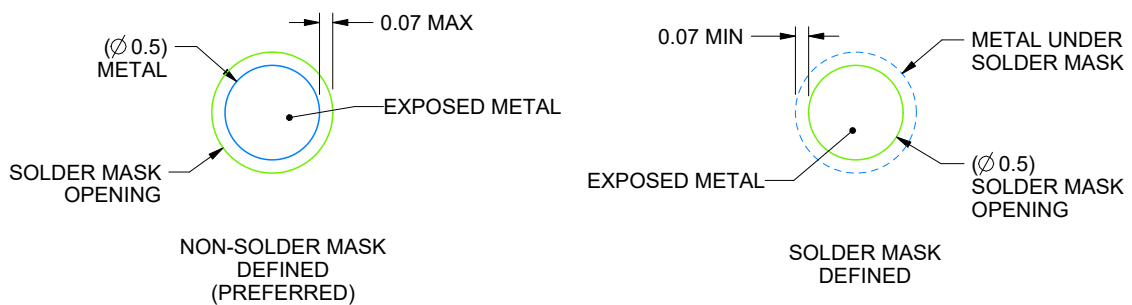
ALJ0256A

FCBGA - 3.31 mm max height

BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:6X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

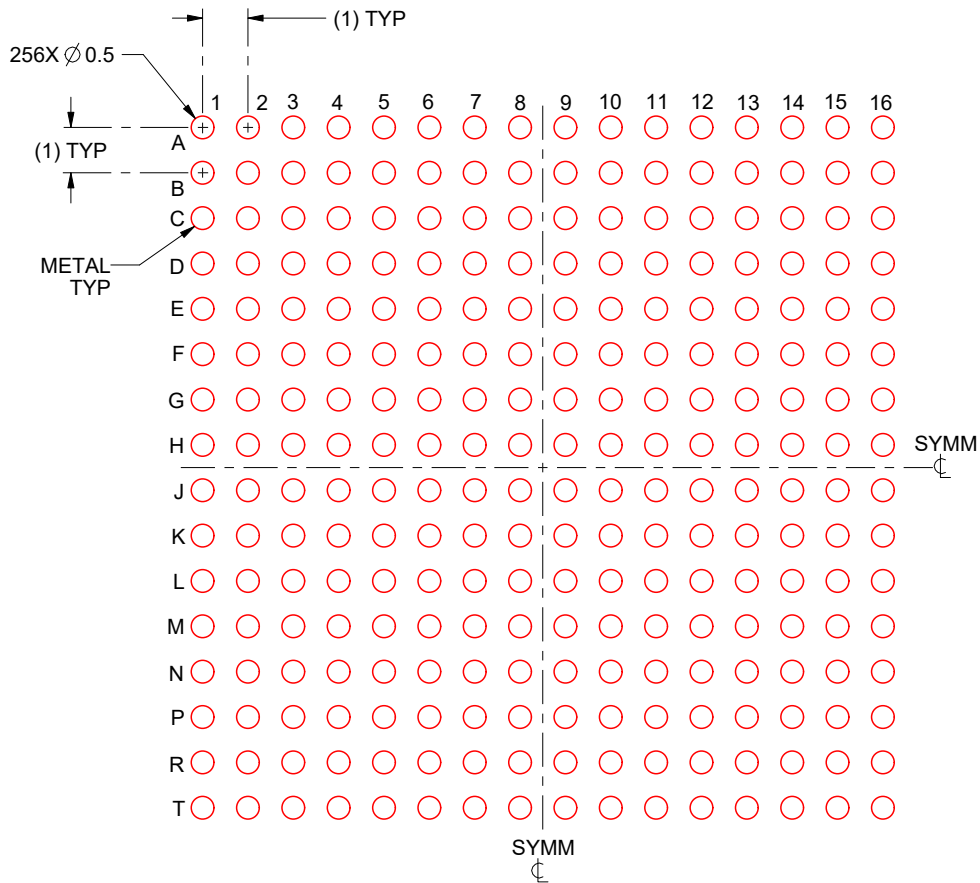
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SPRU811 (www.ti.com/lit/spru811).

EXAMPLE STENCIL DESIGN

ALJ0256A

FCBGA - 3.31 mm max height

BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.15 mm THICK STENCIL
SCALE: 6X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2183671	10/25/2019	K. LEWIS / K. SINCERBOX
B	3.31/2.85 WAS 3.31 MAX;	2199992	05/26/2022	S. O'CONNOR / K. SINCERBOX